

"Half-Bridge" IGBT INT-A-PAK, (Standard Speed IGBT), 100 A



INT-A-PAK

PRODUCT SUMMARY				
V _{CES}	600 V			
I _C DC	220 A			
V _{CE(on)} at 100 A, 25 °C	1.11 V			
Speed	DC to 1 kHz			
Package	INT-A-PAK			
Circuit	Half bridge			

FEATURES

- Standard speed PT IGBT technology
- · Optimized for hard switching speed
- FRED Pt® antiparallel diodes with fast recovery
- Very low conduction losses
- Al₂O₃ DBC
- UL approved file E78996



- Designed for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- Optimized for high current inverter stages (AC TIG welding machines)
- Direct mounting to heatsink
- Very low junction to case thermal resistance
- Low EMI

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V _{CES}		600	V	
O a di a cara di a da cara di a	1	T _C = 25 °C	220		
Continuous collector current	I _C	T _C = 130 °C	100	Α	
Pulsed collector current	I _{CM}		440	A	
Peak switching current	I _{LM}		440		
Gate to emitter voltage	V_{GE}		± 20	V	
RMS isolation voltage	V _{ISOL}	Any terminal to case, t = 1 min	2500	V	
Maximum power dissipation	P _D	T _C = 25 °C	780	W	
		T _C = 100 °C	312	VV	
Operating junction temperature range	TJ		-40 to +150	°C	
Storage temperature range	T _{Stg}		-40 to +125		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V _{BR(CES)}	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	600	-	-		
Collector to emitter voltage		V _{GE} = 15 V, I _C = 100 A	-	1.11	1.28	1	
	V _{CE(on)}	I _C = 200 A	-	1.39	-	V	
		V _{GE} = 15 V, I _C = 100 A, T _J = 125 °C	-	1.08	1.22		
Gate threshold voltage	V _{GE(th)}	I _C = 0.25 mA	3	-	6		
Collector to emitter leakage current	I _{CES}	V _{GE} = 0 V, V _{CE} = 600 V	-	-	1	mA	
		V _{GE} = 0 V, V _{CE} = 600 V, T _J = 125 °C	-	-	10		
Diode forward voltage drop	V_{FM}	I _C = 100 A, V _{GE} = 0 V	-	1.44	1.96	V	
		I _C = 100 A, V _{GE} = 0 V, T _J = 125 °C	-	1.25	1.54]	
Gate to emitter leakage current	I _{GES}	V _{GE} = ± 20 V	-	-	± 250	nA	

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SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge	Qg	I _C = 100 A	-	640	700	
Gate to emitter charge	Q _{ge}	V _{CC} = 400 V	-	108	120	nC
Gate to collector charge	Q _{gc}	V _{GE} = 15 V	-	230	300	
Rise time	t _r	1 100 A	-	0.45	-	
Fall time	t _f	$I_C = 100 \text{ A}$ $V_{CC} = 480 \text{ V}$	-	1.0	-	μs
Turn-on switching energy	E _{on}	V _{GE} = 15 V	-	4	6	
Turn-off switching energy	E _{off}	$R_g = 15 \Omega$ $T_{.1} = 25 ^{\circ}C$	-	23	29	1
Total switching energy	E _{ts}	1 1 = 25 C	-	27	35	
Turn-on switching energy	E _{on}	I _C = 100 A, V _{CC} = 480 V	-	6	12	mJ
Turn-off switching energy	E _{off}	$V_{GE} = 15 \text{ V}, R_g = 15 \Omega$	-	35	40	
Total switching energy	E _{ts}	T _J = 125 °C	-	41	52	
Input capacitance	C _{ies}	V _{GF} = 0 V		16 250	-	
Output capacitance	C _{oes}	V _{CC} = 30 V	-	1040	-	рF
Reverse transfer capacitance	C _{res}	f = 1.0 MHz	-	190	-	
Diode reverse recovery time	t _{rr}	I _E = 50 A		91	155	ns
Diode peak reverse current	I _{rr}	$dI_F/dt = 200 A/\mu s$	-	10.6	15	Α
Diode recovery charge	Q _{rr}	$V_{rr} = 200 \text{ V}$	-	500	900	nC
Diode reverse recovery time	t _{rr}	I _E = 50 A	-	180	344	ns
Diode peak reverse current	I _{rr}	dl _F /dt = 200 A/µs	-	17	20.5	Α
Diode recovery charge	Q _{rr}	V _{rr} = 200 V, T _J = 125 °C	-	1633	2315	nC

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range		TJ	-40	-	150	°C
Storage temperature range		T _{Stg}	-40	-	125	
Junction to case	per switch	R _{thJC}	-	-	0.16	°C/W
	per diode		-	-	0.48	
Case to sink per module		R _{thCS}	-	0.1	-	
Mounting torque	case to heatsink		-	-	4	Nm
	case to terminal 1, 2, 3		-	-	3	INIII
Weight			-	185	-	g

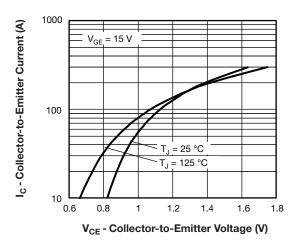


Fig. 1 - Typical Output Characteristics

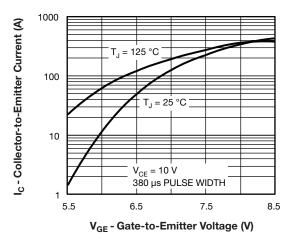


Fig. 2 - Typical Transfer Characteristics

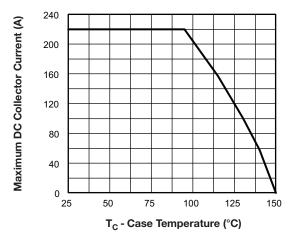


Fig. 3 - Maximum Collector Current vs. Case Temperature

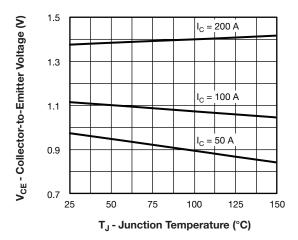


Fig. 4 - Typical Collector to Emitter Voltage vs. Junction Temperature

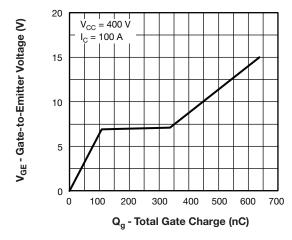


Fig. 5 - Typical Gate Charge vs. Gate to Emitter Voltage

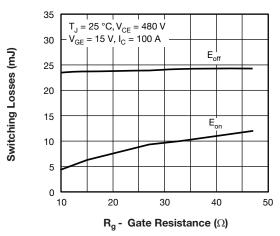


Fig. 6 - Typical Switching Losses vs. Gate Resistance



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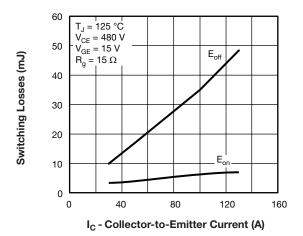


Fig. 7 - Typical Switching Losses vs. Collector to Emitter Current

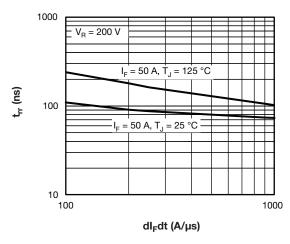


Fig. 9 - Typical Reverse Recovery Time vs. dl_F/dt

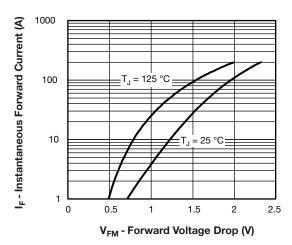


Fig. 8 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

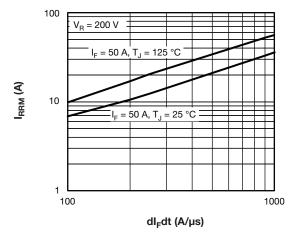


Fig. 10 - Typical Reverse Recovery Current vs. dl_F/dt

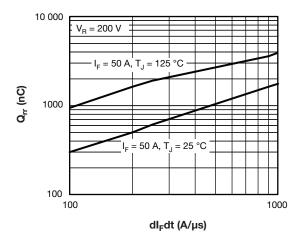
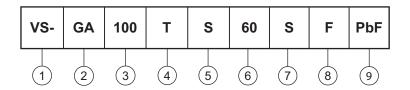


Fig. 11 - Typical Stored Charge vs. dl_F/dt



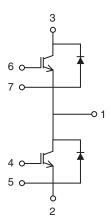
ORDERING INFORMATION TABLE

Device code



- Vishay Semiconductors product
- 2 Essential part number IGBT modules
- Current rating (100 = 100 A)
- Circuit configuration (T = Half bridge)
- 5 INT-A-PAK
 - Voltage code (60 = 600 V)
- 7 Speed/type (S = Standard speed IGBT)
- 8 Diode type
- 9 None = Standard production; PbF = Lead (Pb)-free

CIRCUIT CONFIGURATION

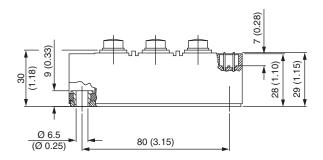


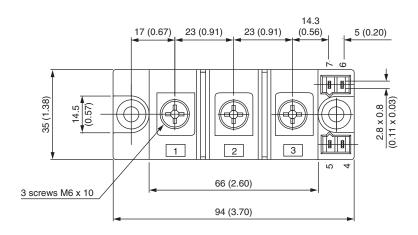
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95173			

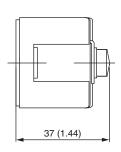


INT-A-PAK IGBT

DIMENSIONS in millimeters (inches)









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